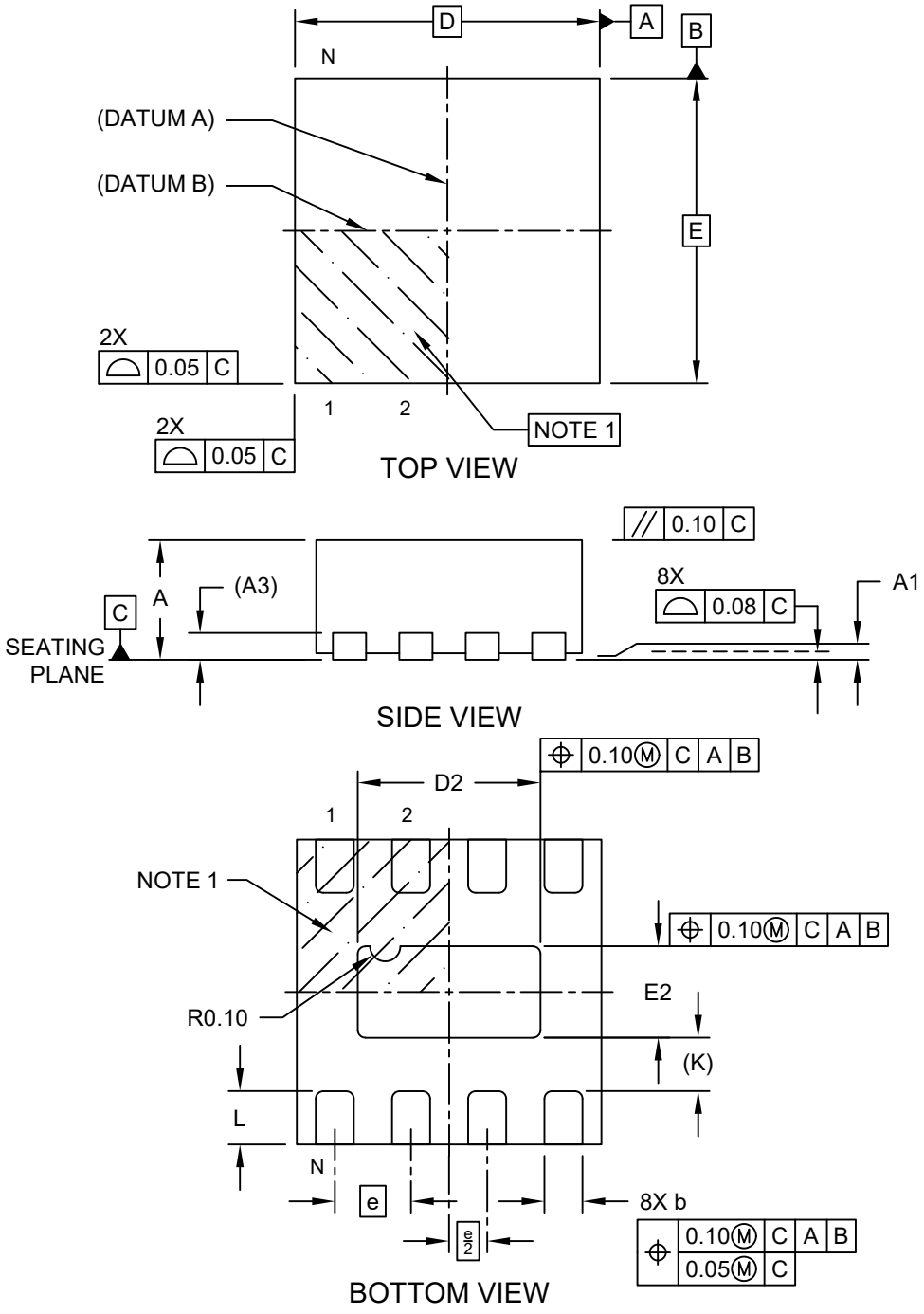
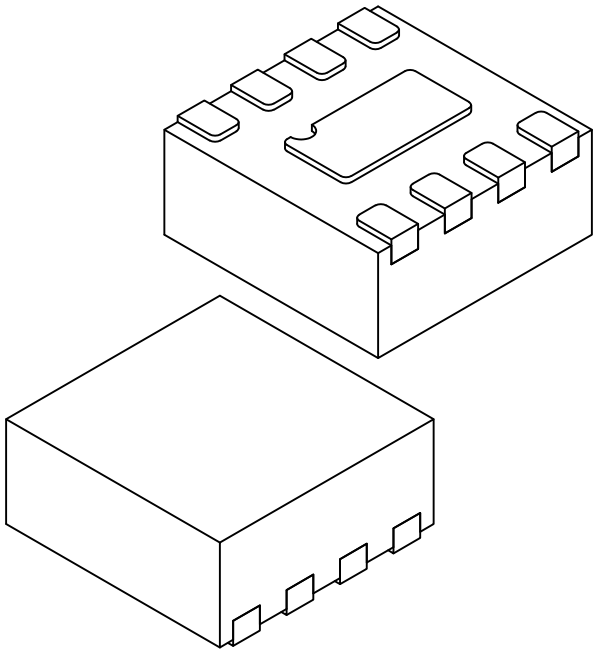
8-Lead Very Thin Plastic Dual Flat, No Lead Package (H2A) - 2x2x0.9 mm Body [VDFN] With 1.20x0.6 mm Exposed Pad

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



8-Lead Very Thin Plastic Dual Flat, No Lead Package (H2A) - 2x2x.9 mm Body [VDFN] With 1.20x0.6 mm Exposed Pad

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



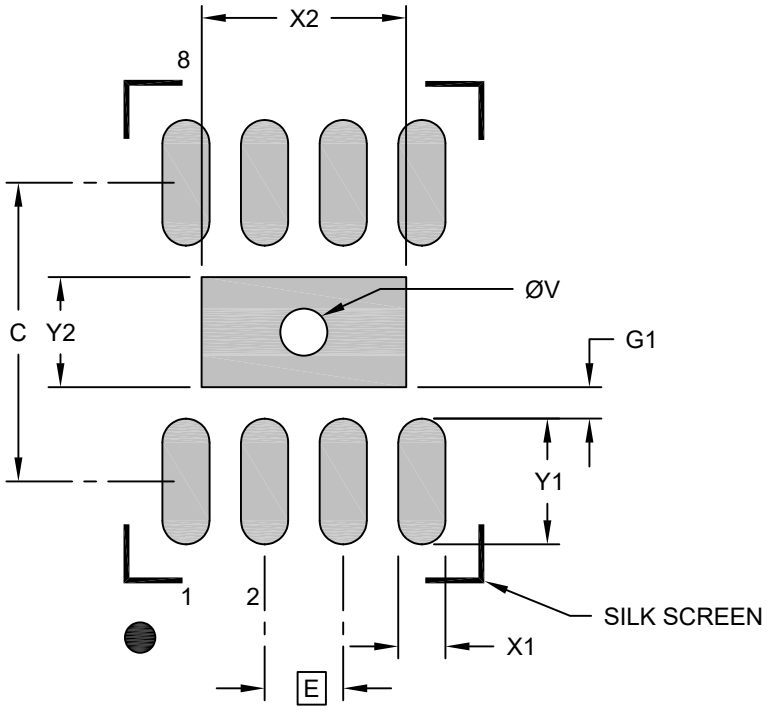
Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		8	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.85	0.90
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.203 REF	
Overall Length	D		2.00 BSC	
Exposed Pad Length	D2	1.10	1.20	1.30
Overall Width	E		2.00 BSC	
Exposed Pad Width	E2	0.50	0.60	0.70
Terminal Width	b	0.20	0.25	0.30
Terminal Length	L	0.30	0.35	0.40
Terminal-to-Exposed-Pad	K		0.35 REF	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

8-Lead Very Thin Plastic Dual Flat, No Lead Package (H2A) - 2x2 mm Body [VDFN] Micrel Legacy Package

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Optional Center Pad Width	X2			1.30
Optional Center Pad Length	Y2			0.70
Contact Pad Spacing	C		1.90	
Contact Pad Width (X8)	X1			0.30
Contact Pad Length (X8)	Y1			0.80
Contact Pad to Center Pad (X8)	G1	0.20		
Thermal Via Diameter	V	0.27	0.30	0.33

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-3247 Rev. B